

REMARKS

Reconsideration and allowance of the present application are respectfully requested. Claims 15-19 and 21-28 remain pending in the application. By this Amendment claim 15 is amended.

Applicants note with appreciation the Examiner's indications in numbered paragraph 3, page 3 of the final Office Action, that claims 16-19 and 21-28 are allowed. Applicants have amended claim 15 to place the application in condition for allowance.

In numbered paragraph 2, page 2 of the final Office Action, independent claim 15 is rejected as being anticipated by U.S. 2004/0102063 (Yin et al.). This rejection is respectfully traversed.

Applicants have previously discussed of record an electrical contact arrangement, comprising a first electrically conductive contact pad, a second electrically conductive contact pad, and an electrically conductive connection between the first and second contact pads. Further, Applicants have disclosed that in order to prevent the contact tip of the pressure contact spring from penetrating too deeply into a contact pad of the contact arrangement under increased spring pressure, the electrically conductive contact pad has a barrier layer, which is arranged underneath the surface layer and consists of a material that is harder than the material of this surface layer (e.g., page 4, lines 19-25).

The foregoing features are broadly encompassed by claim 15, which recites an electrical contact arrangement, including, among other features, an electrical pressure contact spring comprising a first contacting region for contacting a first electrically conductive contact pad, a rounded contact tip being arranged in the first

contacting region for contacting the contact pad, wherein a wire is bent in the first contacting region, wherein this wire bend forms the contact tip, and wherein at least the first contact pad includes a barrier layer arranged underneath a surface layer such that the contact tip of the pressure contact spring is prevented from penetrating through the barrier layer when it penetrates into said surface layer.

The Yin et al. publication discloses that a terminal 11 has a contact tip 114 for point contact with a contact 20 of a circuit board 2 (paragraph 0023)). However, the Yin et al. disclosure is silent as to a multilayered contact pad. The Yin et al. publication would not have taught or suggested at least the first contact pad including a barrier layer arranged underneath a surface layer such that the contact tip of the pressure contact spring is prevented from penetrating through the barrier layer when it penetrates into said surface layer, as recited in claim 15.

For the foregoing reasons, Applicants' independent claim 15 is allowable. As such, the present application is in condition for allowance.

All objections and rejections raised in the Office Action having been addressed, it is respectfully submitted that the application is in condition for allowance and a Notice of Allowance is respectfully solicited.

Respectfully submitted,

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Date: April 20, 2007

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